ASSOCIATION CONN	Material Comp © Copyright 2005. international and Pa	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute					* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				ials and Mfg Information			
Supplier Info	formation													
Company name*				ompany unique ID			Unique ID Authority				Response Date*			
onsemi											2023-06-08			
Contact Name		Title - Contact			1	Phone - Contact*				Email - Contact*				
Product-Env-S	Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
uthorized Rep	presentative*	Title - Representative			1	Phone - Representative*				Email - Representative*				
Product-Env-S	Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Req	quester Item Number	Mfr Item	Number	Mfr Item Name			Effective Date	Versio	n :	Manufacturing Site		Weight*	UOM	Unit Type
		LC05111C16MTTTG 1 cell LiB Pro		1 cell LiB Protecti	3 Protection IC		2023-06-08 PHM		PHM 2		26.64	mg	Each	
Ianufacturi	ring Proccess Informa	ntion												
Terminal Plating / Grid Array Material		Terminal Base Alloy J-STI		-STD-020 M	SL Rating	Peak Process Body Temp		Temperatu	ature Max Time at Peak Tem		ture Numb	er of Reflow Cyc	eles	
contains Bi		CU Alloy 3		3		260 C		C	30	secon	ids 3			
omments														
TTENTION:	MSL 3 Rated item require	es Bake and D	ry Pack (after	electrical test)										
or more infori	mation regarding material	l composition	please refer to	page 3										

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Priective 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Standard Terms andConditions of Sale applicable to such part shall apply.										
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	es per the definition above except for selected exemp	otions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required f Requester) and click on Submit Form to ha		'Accepted" on the Supplier Acceptance drop-dow	n. This will display the signature area. Digita	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	astislav Drska	-6_								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	2.41	mg	Supplier	Silicon (Si)	7440-21-3		2.41	mg
Die Attach Solder	0.89	mg	Supplier	Silver (Ag)	7440-22-4		0.0223	mg
			A	Lead (Pb)	7439-92-1	7a	0.8232	mg
			Supplier	Tin (Sn)	7440-31-5		0.0445	mg
Lead Frame	12.04	mg	Supplier	Silver (Ag)	7440-22-4		0.3612	mg
			Supplier	Tin (Sn)	7440-31-5		0.0181	mg
			Supplier	Copper (Cu)	7440-50-8		11.6607	mg
Mold Compound-Black	10.73	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		1.073	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0536	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		1.5558	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		6.9745	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		1.073	mg
Plating	0.54	mg	В	Bismuth (Bi)	7440-69-9		0.0041	mg
			Supplier	Tin (Sn)	7440-31-5		0.536	mg
Wire Bond - Au	0.03	mg	Supplier	Gold (Au)	7440-57-5		0.03	mg